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TMRC 2021

The 32nd Magnetic Recording Conference

August 16-19 · VIRTUAL, <https://www.dssc.ece.cmu.edu/TMRC2021/index.html>

CALL FOR NOMINATIONS

The 32nd Magnetic Recording Conference will be held **VIRTUALLY** on August 16-19, 2021. The focus of TMRC 2021 is **Solid State Magnetic Memory and Recording Technologies for >3 Tbits/in²**

Approximately 36 invited papers of the highest quality will be presented orally at the conference and will later be published in the IEEE Transactions on Magnetics. What used to be the poster session will now be a contributed session to be presented in standard oral format. Presenters of invited & contributed talks are encouraged for publication.

Topics of interest include:

- Solid State Memory – Devices and Applications
 - Spin Transfer Torque-Magnetic Random Access Memory (MTJ cell, MRAM chip manufacturing and roadmap)
 - MRAM– New Physics & Materials (MRAM architecture, VC-MRAM, SOT-MRAM, TI & 2D materials)
 - Magnetic Logic
- Advanced Generation Recording Technologies
 - Heat Assisted Magnetic Recording (HAMR System, Head/Media and HDI)
 - Microwave-Assisted Magnetic Recording (MAMR), Energy-Assisted Magnetic Recording (EAMR)
 - Alternative Magnetic Recording Technologies (SMR, TDMR, HIMR, Heated-dot, Tape, All Optical Switching)
 - Advanced Magnetic Recording for > 3 Tbits/in² including Readers, Writers, Servo, Tribology, HDI, Signal Processing
- Recording and Memory Fundamentals (Metrology, Tooling, Materials, Recording Physics)

By completing this [online form](#), nominations for invited speakers are submitted to the Program Chairs. The deadline to submit nominations is March 26, 2021.

To receive information via email, please subscribe [here!](#)

TMRC 2021 is sponsored by the IEEE Magnetics Society and co-sponsored by the Data Storage Systems Center (CMU), the Center for Memory and Recording Research (UCSD), the Center for Micromagnetics & Information Technologies (Univ. of Minnesota), the Center for Magnetic Nanotechnology (Stanford), and the Computer Mechanics Laboratory (UC Berkeley).